



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Wayne Glenn Renken
Title: System and Method for Heating and Cooling Wafer at Accelerated Rates
Application No.: 10/619,731 Filing Date: July 15, 2003
Examiner: Unknown Group Art Unit: 1725
Docket No.: SENS.007US1 Conf. No.: 7022

Certificate of Mailing Under 37 CFR 1.8

I hereby certify that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on January 21, 2004

Mary S. Buggin
Signature

Mail Stop Missing Parts
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

VOLUNTARY AMENDMENT

Dear Sir:

Please amend the above-identified application as follows:

Amendments to the Specification begin on page 2 of this paper.

Remarks begin on page 3 of this paper.